



Product/Process Change Notice - PCN 19_0109 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: AD8152 Assembly Site Transfer and Data Sheet Revision

Publication Date: 15-May-2019

Effectivity Date: 17-Aug-2019 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change:

- 1) Change of package type from Super Ball Grid Array (SBGA) to Thermally Enhanced Ball Grid Array (BGA_ED)
- 2) Change die interconnect type from Wire Bond (WB) to Flip Chip (FC)
- 3) Assembly site transfer from AMKOR Philippines to STATS ChipPAC Korea
- 4) Change in overall package thickness from 1.7mm max to 2.04mm max
- 5) Change in data sheet includes a change in Package Outline Drawing (POD) and thermal resistance section. See attached detailed change description.

Note: New package is pin-pin compatible with old package

Reason For Change:

Due to laminate obsolescence; Amkor, Philippines is shutting down their line for this type of package. The use of ADI qualified STATS ChipPAC, Korea as an assembly site for this package will ensure continued source of product supply. ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations

Impact of the change (positive or negative) on fit, form, function & reliability:

The height of the product has increased as noted in the Description of Change field. There is no change to the functionality or reliability of the product. The revised product is fully pin and code compatible.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary. Product data sheet changes will be reflected in data sheet RevB.

Supporting Documents

Attachment 1: Type: Detailed Change Description

ADI_PCN_19_0109_Rev_-_AD8152 PCN_Detailed Change Description.pptx

Attachment 2: Type: Qualification Results Summary

ADI_PCN_19_0109_Rev_-_Qualification Results Summary of AD8152 BGA_ED.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:
PCN_Americas@analog.com

Europe:
PCN_Europe@analog.com

Japan:
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Rest of Asia:
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Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (1)

AD8152 / AD8152JBPZ				
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Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	15-May-2019	17-Aug-2019	Initial Release

Analog Devices, Inc.

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